



Material Content Data Sheet



Halogen-Free

Sales Product Name	BTF3080EJ	Issued	24. June 2021
MA#	MA005549600		
Package	PG-TDSO-8-31	Weight*	67.48 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	1.592	2.36	2.36	23598	23598
leadframe	inorganic material	phosphorus	7723-14-0	0.009	0.01		141	
	non noble metal	zinc	7440-66-6	0.038	0.06		563	
	non noble metal	iron	7439-89-6	0.760	1.13		11259	
	non noble metal	copper	7440-50-8	30.851	45.72	46.92	457155	469118
wire	non noble metal	copper	7440-50-8	0.323	0.48	0.48	4791	4791
encapsulation	organic material	carbon black	1333-86-4	0.096	0.14		1422	
	plastics	epoxy resin	-	3.742	5.54		55447	
	inorganic material	silicondioxide	60676-86-0	28.144	41.70	47.38	417039	473908
leadfinish	non noble metal	tin	7440-31-5	0.497	0.74	0.74	7368	7368
plating	noble metal	silver	7440-22-4	0.825	1.22	1.22	12222	12222
glue	plastics	epoxy resin	-	0.106	0.16		1574	
	noble metal	silver	7440-22-4	0.501	0.74	0.90	7421	8995
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
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This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption.

Company	Infineon Technologies AG
Address	81726 Neubiberg
Internet	www.infineon.com